SPECIFICATION FOR APPROVAL

DESCRIPTION: 1.25mm PITCH	WIRE TO BOARD SMT, R/A TYPE SINGLE ROW
CUSTOMER PROD.NO/DWG.NO:	
E&T PROD.NO:	3800K-XXXX-03,33,04,05X
APPROVAL SHEET NO:	
E&T DWG. NO./DOCUMENT:	3800K-XXXX-03,33,04.05X
	DEV: AA

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES					



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.

Title: 1.25mm WIRE TO BOARD SMT, R/A TYPE SINGLE ROW

Rele	ase History	Title: Pitch 1	.25mm Wire To Board Connector, R/A,	SMT Type Single Row.		
A4	10,18,2012'		This Document Contains Information That Is Proprietary To			
Rev	Description	E&T	And Should Not Be Used Without Wri	tten Permission		
Document No.			Prepared By: Hill Chang	Date: 12,30,2008'		
3800K-XXXX-03,33,04,05X		8800K_XXXX_03 33 04 05X Checked By:		Date: 18 75/2		
2000	TRIBITATE OF	,00,0 1,002x	Approved By:	Date:		

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	Gr	oup)			
	lest of Examination	A	В	C	D	Е	F	G	Н	Ι	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,3	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	Insertion and Withdrawal Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						2		2			
13	Resistance To Soldering Heat									2		
14	Salt Spray							3				
15	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the pitch 1.25 mm WIRE TO BOARD SMT connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
1.25mm WIRE TO BOARD Connector, R/A, SMT Type Single Row	3800K-XXXX-03,33,04,05X

3. RATINGS:

Item	S	tandard
Rated Voltage (MAX.)	125 V	AC(rms)/DC
Rated Current (MAX.)	1 A	AC(IIIIs)/DC
Operating Temperature Range	-40 ⁰ (C ~ +85 ⁰ C*

^{*}Including terminal temperature rise

4.PERFORMANCE:

4- 1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 10 mA . Test Voltage: 20mV Max Test Method: JIS C5402 5.4	20 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 500V DC. Test Method: MIL-STD-202, method 302	100 MΩ Min.
4-1-3	Dielectric Strength	Test Voltage: 500 V AC(rms). Test Time: 60 sec. Test Method: MIL-STD-202, Method 301.	No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement
4-2-1	Insertion and Withdrawal Force	Test Speed: 25±3 mm/min.	See 5-1
4-2-2	Pin Retention Force	Test Speed: 25±3mm/min.	0.5 kgf (Min)

4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Insert and withdraw actuator up to 30cycles at the speed rate of less than 10 cycles/	Contact Re	sistance
4-3-1	Durability	minute.	Initial Value	\leq 20 m Ω
			Final Value	≤40 mΩ
		Amplitude: 1.5 mm P-P Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-2	Vibration	Duration: 2 hours in each X.Y.Z axes Test Method: MIL-STD-202F, Method 201	Contact Resistance	≦40 mΩ
			Discontinuity	1µsec MAX
4-3-3	Heat	Temperature: $85\pm2^{\circ}$ C Duration: 96 hours	Appearance	No Damage
4-5-5	Resistance	Test Method: MIL-STD-202, Method 108.	Contact Resistance	≦40 mΩ
4-3-4	Cold	Temperature: -40±3°C Duration: 96 hours Test Method: JIS C60068-2-1	Appearance	No Damage
4-0-4	Resistance	Test Method. 013 000000-2-1	Contact Resistance	≦40 mΩ
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-5	Humidity	Duration: 96 hours Test Method: MIL-STD-202F , Method 103	Contact Resistance	≦40 mΩ
7 0 0	Trainingity		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3

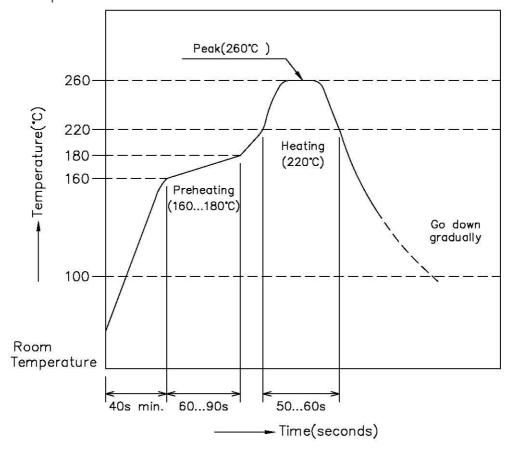
	Item	Test Condition	Requi	rement
4-3-6	Solder Ability	Soldering Time : 3 ± 0.5 sec Solder Temperature : $245\pm5^{\circ}$ C Test Method: MIL-STD-202F , Method 208	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-7	Resistance To Soldering Heat	Soldering Time : 10 ± 0.5 sec Solder Temperature : $260\pm5^{\circ}$ C Test Method: MIL-STD-202F , Method 210A	Appearance	No Damage
		Steam Aging Temperature : 98±2°C Duration: 8 hours Solder Temperature : 245±5°C	Appearance	No Damage
4-3-8	Steam Aging	Soldering Time: 3±0.5 sec Test Method: MIL-STD-202F, Method 208	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-9	Salt Spray	Chamber Temperature: 35±2°C Air Tank Temperature: 47±1°C Salt Solution: 5 ± 1% Duration: 48 hours	Appearance	No Damage
	oun opray	Test Method: MIL-STD-202, Method 101D	Contact Resistance	\leq 40 m Ω
4-3-10	Temperature	5 cycles of : a) - 55 $\pm 3^{\circ}$ C 30 minutes b) +105 $\pm 3^{\circ}$ C 30 minutes	Appearance	No Damage
7-3-10	Cycling	Test Method: JIS C0025	Contact Resistance	\leq 40 m Ω

5-1 Insertion and \Withdrawal Force

NO of	In	sertion For	·ce	Ext	traction Fo	rce
CKT	(Kgf,Max)				(Kgf,Min)	
	1st	6th	30th	1st	6th	30th
2	2	1.8	1.6	0.28	0.23	0.18
3	2.5	2.3	2.1	0.3	0.25	0.2
4	3	2.8	2.6	0.33	0.28	0.23
5	3.5	3.3	3.1	0.38	0.33	0.28
6	4	3.8	3.6	0.43	0.38	0.33
7	4.5	4.3	4.1	0.48	0.43	0.38
8	5	4.8	4.6	0.53	0.48	0.43
9	5.5	5.3	5.1	0.56	0.51	0.46
10	6	5.8	5.6	0.59	0.54	0.49
11	6.5	6.3	6.1	0.62	0.57	0.52
12	7	6.8	6.6	0.65	0.6	0.55
13	7.5	7.3	7.1	0.68	0.63	0.58
14	8	7.8	7.6	0.71	0.66	0.61
15	8.5	8.3	8.1	0.74	0.69	0.64
16	9	8.8	8.6	0.77	0.72	0.67
20	11	10.8	10.6	0.89	0.84	0.79
25	13.5	13.3	13.1	1.04	0.99	0.94
30	16	15.8	15.6	1.19	1.14	1.09

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



Wire To Board Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's wire to board connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's wire to board connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.
- E&T's wire to board connector is not designed for the mating and unmating of the connectors to be performed under the condition of an active electrical circuit. It may cause a spark and product defect if the connectors are mated and unmated in this way.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).
- Changing recommended pattern causes problems.

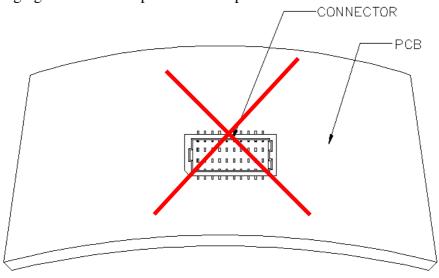


Figure 1.

3. Precautions Crimped Terminal Insertion

- Terminal must be inserted horizontally oriented (see figure 2).
- Do not attempt to insert crimped terminal in any other direction. (see figure 2).

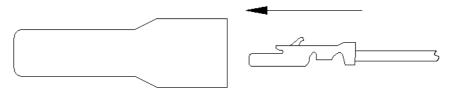
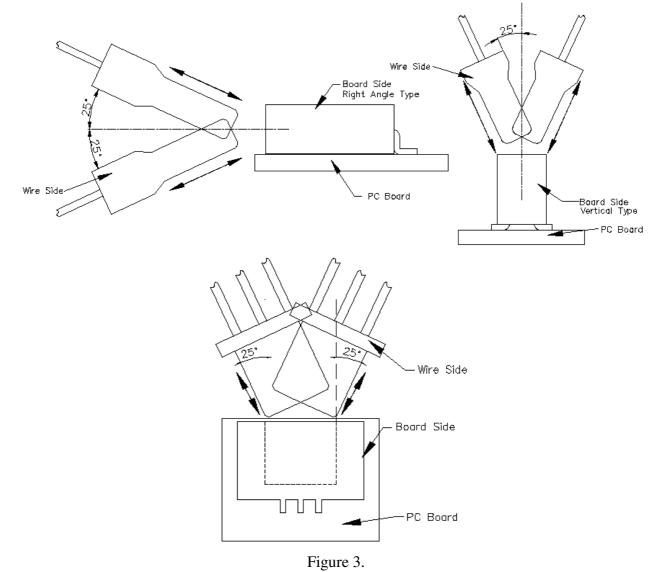


Figure 2.

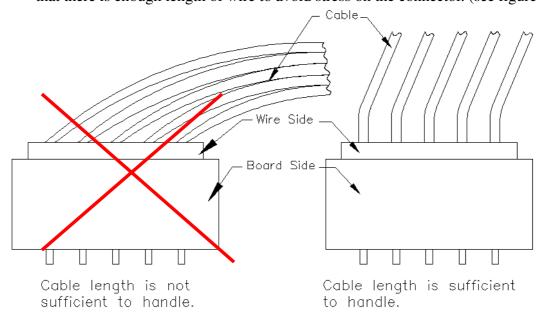
4. Precautions When Inserting or Withdrawal Wire To Board

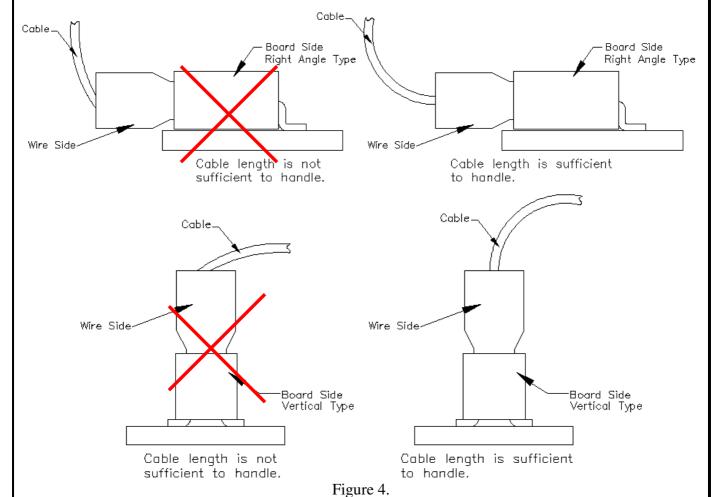
- Do not insert and remove at an angle of 25° or greater. Doing so will cause contact deformation or case damage. (see figure 3).
- Push the wire side connector until firmly closed. At this time, confirm that the wire side connector is mated securely.
- When mounting of connectors, its slant or aberration shall be 3° max.
- Do not insert and remove the connectors when the board side connector is not mounted on the PC board.
- Used Lock type, when removed to connectors, please released positive locks.



5. Precautions Cable Assembly

• The cable assembly should not have a constant stress or pulling force applied on it when it is in the mated condition. Therefore, when designing the wire positioning, please ensure that there is enough length of wire to avoid stress on the connector. (see figure 4).





RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A3	REN120321	Mar-23-2012	KAZ	ADD 33 TYPE
A4	REN121006	OCT-18-2012	Max	ADD 04 & 05 TYPE